

Universität Stuttgart

Institut für Robuste
Leistungshalbleitersysteme

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Bachelorarbeit /
Forschungsarbeit /
HiWi

Beginn: ab sofort

LE

Modellierung von GaN-Transistoren

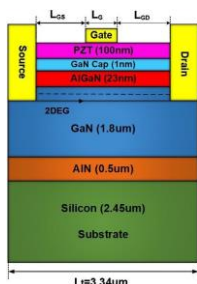
Die Verwendung von Leistungsbau-
elementen aus Galliumnitrid (GaN) in
der Leistungselektronik ermöglicht es,
Systeme zu miniaturisieren und die
Leistungsdichte zu erhöhen. Das elektrische
und thermische Verhalten dieser
Baulemente im Betrieb ist ein
entscheidendes Kriterium bei der Auswahl
der Transistoren. Im Rahmen dieser Arbeit
sollen Modelle für verschiedene GaN-
Leistungshalbleiter erstellt und miteinander
verglichen werden.

Aufgaben

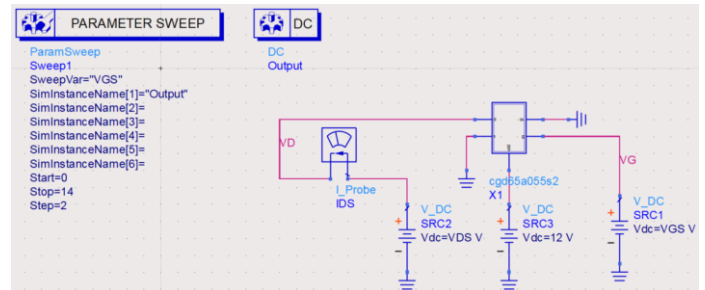
- Ableitung empirischer Modelle aus den
Datenblattkurven der Transistoren.
- Anpassung eines vorhandenen
physikalisch motivierten Modells
(Verilog-A) für die jeweiligen
Transistoren.
- Bewertung der Simulationsergebnisse
der verschiedenen Modelle.
- Durchführung von Messungen zur
Validierung der Modelle.

Ziel

- Durchführung einer Genauigkeitsanalyse
der verschiedenen Modelle.

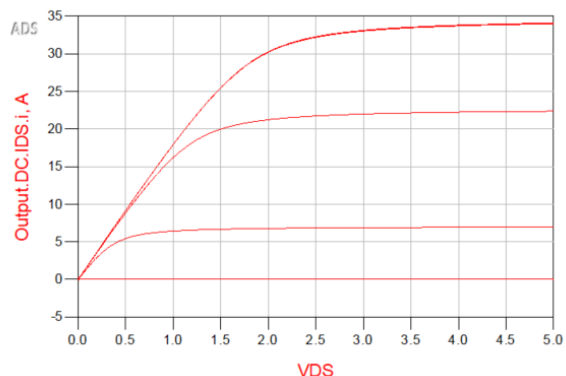


Struktur eines GaN HEMT [1]



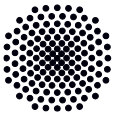
Model in ADS

```
// Gate Current Model ///////////////
if (gatemod == 1) begin
  t0 = V(gi, si)/(njgs*KboQ*Tdev);
  t3 = igsdio + (Tdev/Tnom - 1.0)* ktgs;
  Igs = w1*nf*abs(t3)*(lexp(t0)-1.0);
  t0 = V(gi, di)/(njgd*KboQ*Tdev);
  t3 = igddio + (Tdev/Tnom - 1.0)* ktgd;
  Igd = w1*nf*abs(t3)*(lexp(t0)-1.0);
  I(gi, si) <+ Igs;
  I(gi, di) <+ Igd;
end
```



Ausgangskennlinie





Universität Stuttgart

Institute of Robust Power Semiconductor Systems

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Bachelor Thesis /
Study Thesis /
HiWi

Start: immediately

PE

Modeling of GaN transistors

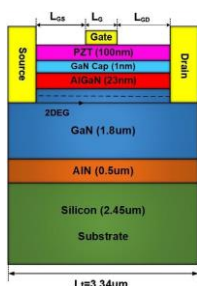
The use of power components made of gallium nitride (GaN) in power electronics makes it possible to miniaturize systems and increase power density. The electrical and thermal behavior of these components during operation is a decisive criterion in the selection of transistors. Within the scope of this work, models for various GaN power semiconductors are to be created and compared with each other.

Tasks

- Derivation of empirical models from the data sheet curves of the transistors.
- Adaptation of an existing physically motivated model (Verilog-A) for the respective transistors.
- Evaluation of the simulation results of the different models.
- Carrying out measurements to validate the models.

Goal

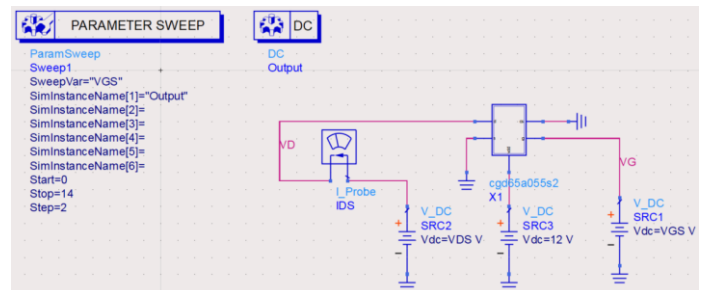
- Carrying out an accuracy analysis of the various models.



Structure of GaN HEMT [1]

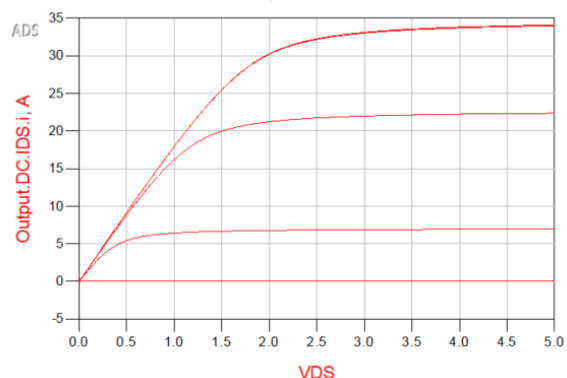
The work includes

- Literature research
- Creation of empirical and physical models of the transistors
- Evaluation of the results
- Validation through measurements
- Documentation of the work



Model in ADS

```
// Gate Current Model ///////////////
if (gatemod == 1) begin
  t0 = V(gi, si) / (njgs * KboQ * Tdev);
  t3 = igsdio + (Tdev / Tnom - 1.0) * ktgs;
  Igs = w * 1 * nf * abs(t3) * (lexp(t0) - 1.0);
  t0 = V(gi, di) / (njgd * KboQ * Tdev);
  t3 = igddio + (Tdev / Tnom - 1.0) * ktgd;
  Igd = w * 1 * nf * abs(t3) * (lexp(t0) - 1.0);
  I(gi, si) <+ Igs;
  I(gi, di) <+ Igd;
end
```



Output characteristics

